



## High Current Density Surface Mount Schottky Barrier Rectifiers

### eSMP™ Series



#### TO-277A (SMPC)



### PRIMARY CHARACTERISTICS

|                        |           |
|------------------------|-----------|
| $I_{F(AV)}$            | 2 x 6.0 A |
| $V_{RRM}$              | 40 V      |
| $I_{FSM}$              | 150 A     |
| $E_{AS}$               | 20 mJ     |
| $V_F$ at $I_F = 1.0$ A | 0.24 V    |
| $T_J$ max.             | 125 °C    |

### TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, dc-to-dc converters and polarity protection applications.

### FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency
- Low thermal resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- **Halogen-free according to IEC 61249-2-21 definition**

AUTOMOTIVE  
GRADE  
Available



RoHS  
COMPLIANT  
HALOGEN  
FREE

### MECHANICAL DATA

**Case:** TO-277A (SMPC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free and RoHS compliant, commercial grade

Base P/NHM3 - halogen-free and RoHS compliant, automotive grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

| PARAMETER   | SYMBOL         | SS12P4C       | UNIT |
|---|----------------|---------------|------|
| Device marking code   |                | S124C         |      |
| Maximum repetitive peak reverse voltage   | $V_{RRM}$      | 40            | V    |
| Maximum average forward rectified current (fig. 1) <sup>(1)</sup> total device per diode    | $I_{F(AV)}$    | 12<br>6.0     | A    |
| Maximum average forward rectified current <sup>(2)</sup> total device                       | $I_{F(AV)}$    | 3.5           | A    |
| Peak forward surge current 10 ms single half sine-wave superimposed on rated load per diode | $I_{FSM}$      | 150           | A    |
| Non-repetitive avalanche energy at $T_J = 25$ °C, $L = 60$ mH per diode                     | $E_{AS}$       | 20            | mJ   |
| Peak repetitive reverse current at $t_p = 2$ μs, 1 kHz, at $T_J = 25$ °C per diode          | $I_{RRM}$      | 1.0           | A    |
| Operating junction and storage temperature range  | $T_J, T_{STG}$ | - 55 to + 125 | °C   |

#### Notes

(1) Mounted on 30 mm x 30 mm Al P.C.B. with 50 mm x 25 mm x 100 mm fin heat sink

(2) Free air, mounted on recommended copper pad area



| ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                      |   |                |             |           |          |
|--|----------------------|---|----------------|-------------|-----------|----------|
| PARAMETER  | TEST CONDITIONS      |   | SYMBOL         | TYP.        | MAX.      | UNIT     |
| Instantaneous forward voltage per diode <sup>(1)</sup>                     | I <sub>F</sub> = 1 A | T <sub>A</sub> = 25 °C                            | V <sub>F</sub> | 0.34        | -         | V        |
|  | I <sub>F</sub> = 3 A |   |                | 0.40        | -         |          |
|  | I <sub>F</sub> = 6 A |   |                | 0.46        | 0.52      |          |
|  | I <sub>F</sub> = 1 A | T <sub>A</sub> = 100 °C                           |                | 0.24        | -         |          |
|  | I <sub>F</sub> = 3 A |   |                | 0.31        | -         |          |
|  | I <sub>F</sub> = 6 A |   |                | 0.40        | 0.45      |          |
| Reverse current per diode per diode <sup>(2)</sup>                         | Rated V <sub>R</sub> | T <sub>A</sub> = 25 °C<br>T <sub>A</sub> = 100 °C | I <sub>R</sub> | 129<br>11.9 | 500<br>25 | μA<br>mA |
| Typical junction capacitance per diode                                     | 4.0 V, 1 MHz         |   | C <sub>J</sub> | 400         | -         | pF       |

**Notes**

- <sup>(1)</sup> Pulse test: 300 μs pulse width, 1 % duty cycle
- <sup>(2)</sup> Pulse test: Pulse width ≤ 40 ms

| THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                                 |         |      |
|---|---------------------------------|---------|------|
| PARAMETER   | SYMBOL                          | SS12P4C | UNIT |
| Typical thermal resistance per device                                   | R <sub>θJA</sub> <sup>(1)</sup> | 100     | °C/W |
|   | R <sub>θJM</sub> <sup>(2)</sup> | 3       |      |

**Notes**

- <sup>(1)</sup> Free air, mounted on recommended copper pad area. Thermal resistance R<sub>θJA</sub> - junction to ambient.
- <sup>(2)</sup> Mounted on 30 mm x 30 mm Al P.C.B. with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance R<sub>θJM</sub> - junction to mount.

| ORDERING INFORMATION (Example) |                 |                        |               |                                    |
|--------------------------------|-----------------|------------------------|---------------|------------------------------------|
| PREFERRED P/N                  | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| SS12P4C-M3/86A                 | 0.10            | 86A                    | 1500          | 7" diameter plastic tape and reel  |
| SS12P4C-M3/87A                 | 0.10            | 87A                    | 6500          | 13" diameter plastic tape and reel |
| SS12P4CHM3/86A <sup>(1)</sup>  | 0.10            | 86A                    | 1500          | 7" diameter plastic tape and reel  |
| SS12P4CHM3/87A <sup>(1)</sup>  | 0.10            | 87A                    | 6500          | 13" diameter plastic tape and reel |

**Note**

- <sup>(1)</sup> AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25 °C unless otherwise noted)

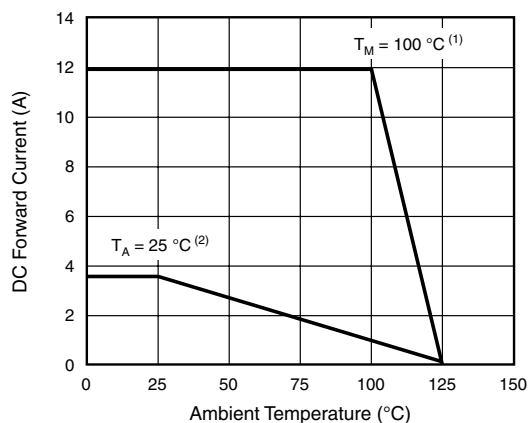


Figure 1. Maximum Forward Current Derating Curve

**Notes**

- <sup>(1)</sup> Mounted on 30 mm x 30 mm Al P.C.B. with 50 mm x 25 mm x 100 mm fin heat sink, T<sub>M</sub> measured at the terminal of cathode band (R<sub>θJM</sub> = 3 °C/W)
- <sup>(2)</sup> Free air, mounted on recommended copper pad area (R<sub>θJA</sub> = 100 °C/W)

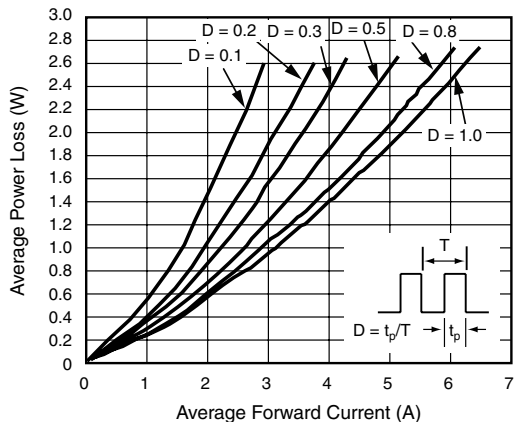


Figure 2. Forward Power Loss Characteristics Per Diode

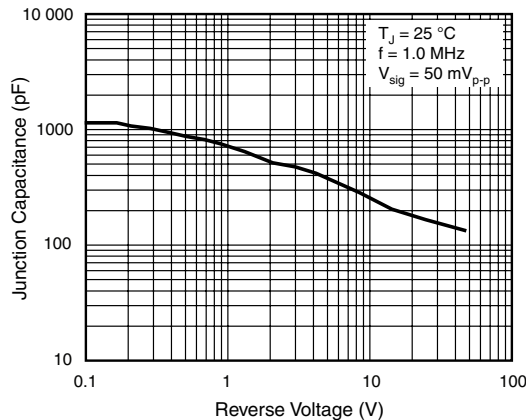


Figure 5. Typical Junction Capacitance Per Diode

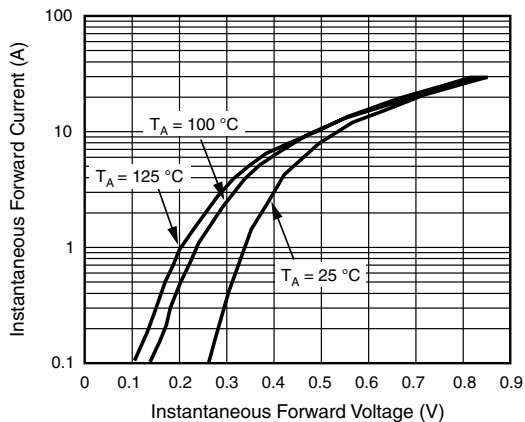


Figure 3. Typical Instantaneous Forward Characteristics Per Diode

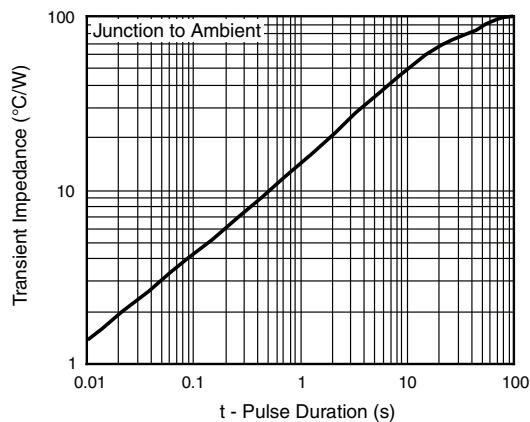


Figure 6. Typical Transient Thermal Impedance Per Device

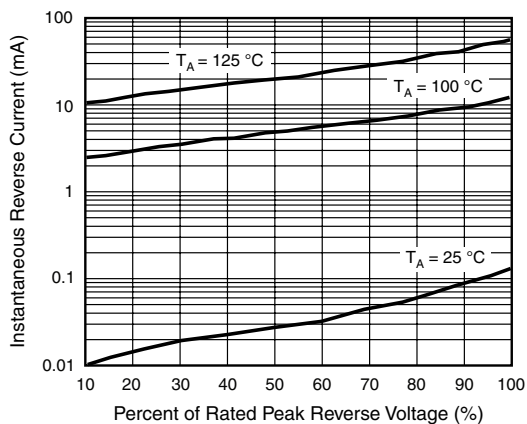
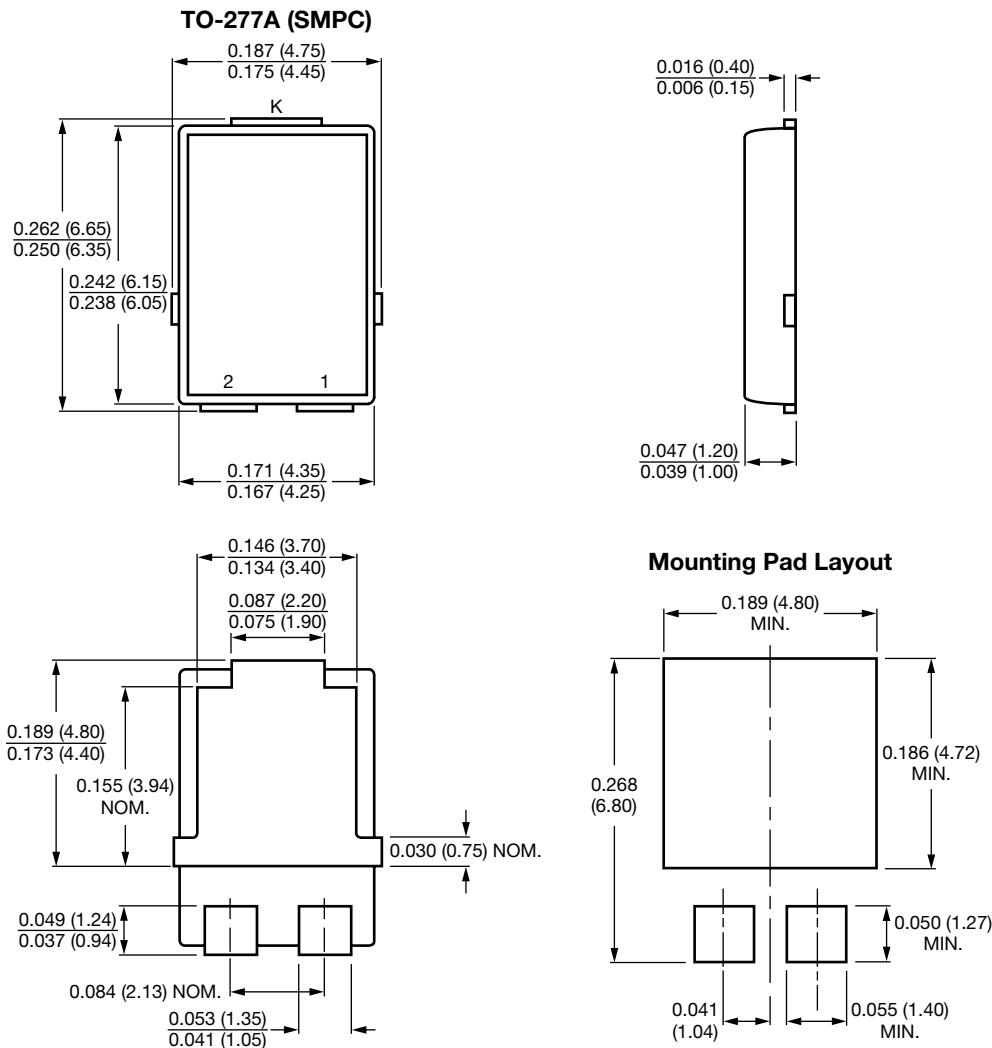


Figure 4. Typical Reverse Leakage Characteristics Per Diode

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



Conform to JEDEC TO-277A



## Disclaimer

All product specifications and data are subject to change without notice.

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